# 2SA1512

# Silicon PNP epitaxial planar type

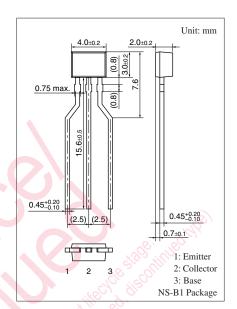
### For low-frequency amplification

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Optimum for low-voltage operation and for converters
- Allowing supply with the radial taping
- Optimum for high-density mounting

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-25	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-20	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-7	V	
Collector current	$I_C$	- 0.5	A	
Peak collector current	$I_{CP}$	-1	A	
Collector power dissipation	P <sub>C</sub>	300	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



## ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

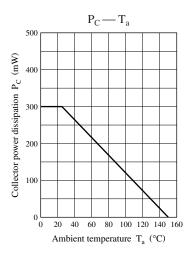
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10 \mu \text{A},  I_{\rm E} = 0$	-25			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -1 \text{ mA}, I_B = 0$	-20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu\text{A},  I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = -25 \text{ V}, I_E = 0$			-100	nA
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -20 \text{ V}, I_B = 0$			-1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = -2 \text{ V}, I_{C} = -0.5 \text{ A}$	90		220	_
	h <sub>FE2</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -1 \text{ A}$	25			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$			- 0.4	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$			-1.2	V
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		15	25	pF
(Common base, input open circuited)						

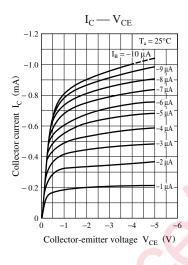
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

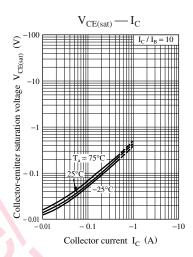
#### 2. \*1: Pulse measurement

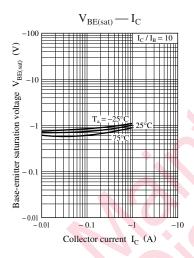
#### \*2: Rank classification

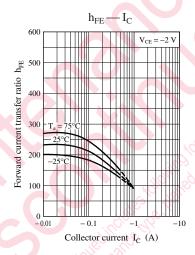
Rank	Q	R
$h_{\rm FE1}$	90 to 155	130 to 220

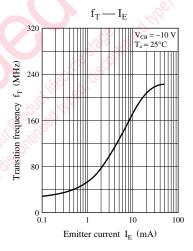


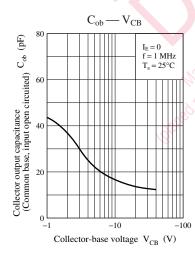












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